

**Generic performance specification
for printed boards**

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*The Institute for
Interconnecting
and Packaging
Electronic Circuits*

IPC-6011

Generic Performance Specification for Printed Boards

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

GENERIC PERFORMANCE SPECIFICATION FOR PRINTED BOARDS

FOREWORD

A PAS is a technical specification not fulfilling the requirements for a standard, but made available to the public and established in an organization operating under given procedures.

IEC-PAS 62214 was submitted by the IPC (The Institute for Interconnecting and Packaging Electronic Circuits) and has been processed by IEC technical committee 52: Printed circuits. It will be further processed by IEC TC 91: Electronics assembly technology.

The text of this PAS is based on the following document:

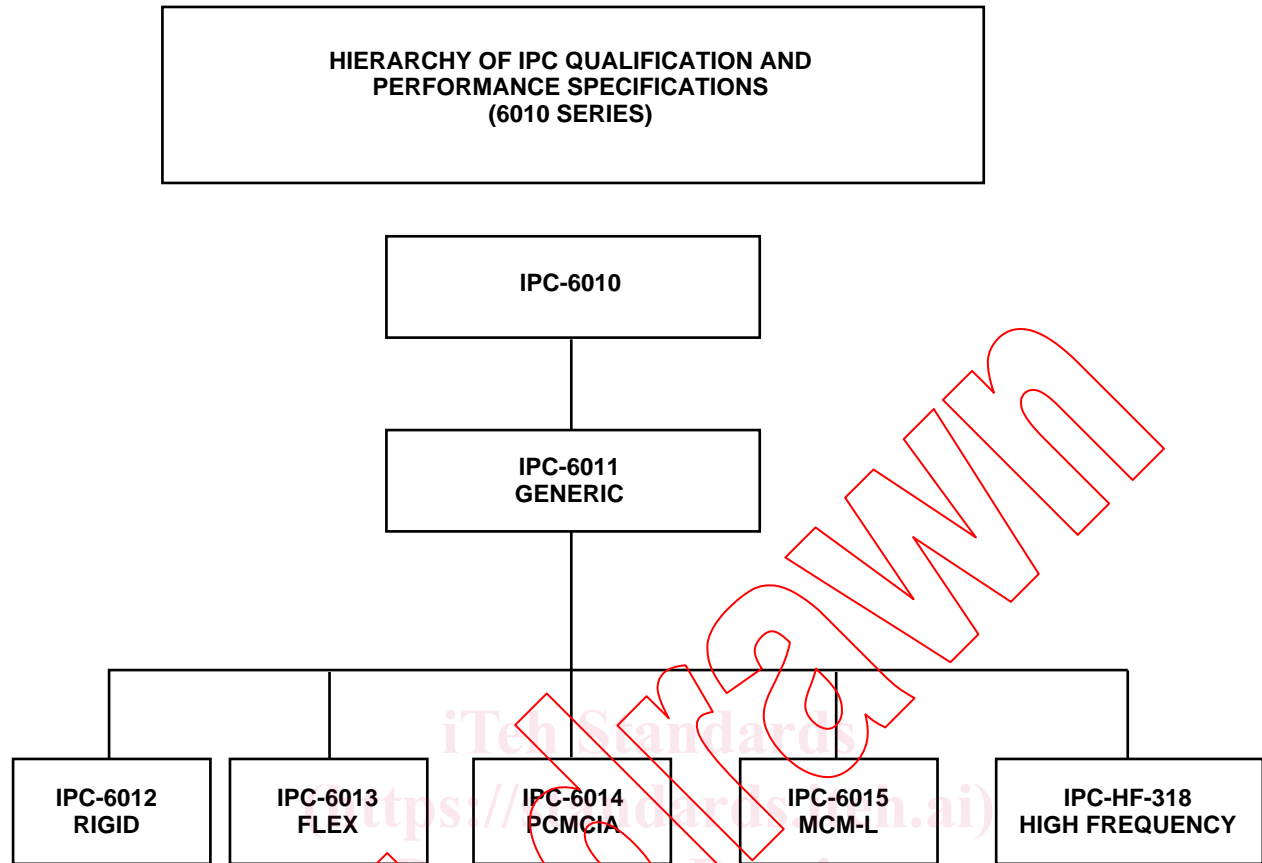
This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document:

Draft PAS	Report on voting
52/872/PAS	52/882/RVD

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Foreword

IPC's documentation strategy is to provide distinct documents that focus on specific aspects of electronic packaging issues. In this regard document sets are used to provide the total information related to a particular electronic packaging topic. A document set is identified by a four digit number that ends in zero (0) (i.e., IPC-6010).

This standard is intended to provide information on the generic specifications for printed boards. This information must also be supplemented by a performance specification that contains the requirements for the chosen technology. When used together, these documents should lead both manufacturer and customer to consistent terms of acceptability.

This document, combined with one of the performance specifications, form the documentation package which supersedes the following:

IPC-6012 supersedes IPC-RB-276

IPC-6013 supersedes IPC-RF-245 and IPC-FC-250

As technology changes, a performance specification will be updated, or new focus specifications will be added to the document set. The IPC invites input on the effectiveness of the documentation and encourages user response through completion of "Suggestions for Improvement" forms at the end of each document.

Acknowledgment

Any Standard involving a complex technology draws material from a vast number of sources. While the principal members of the

Performance Specifications Task Group of the IPC Rigid Printed Board Committee are shown below, it is not possible to include all of those

who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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